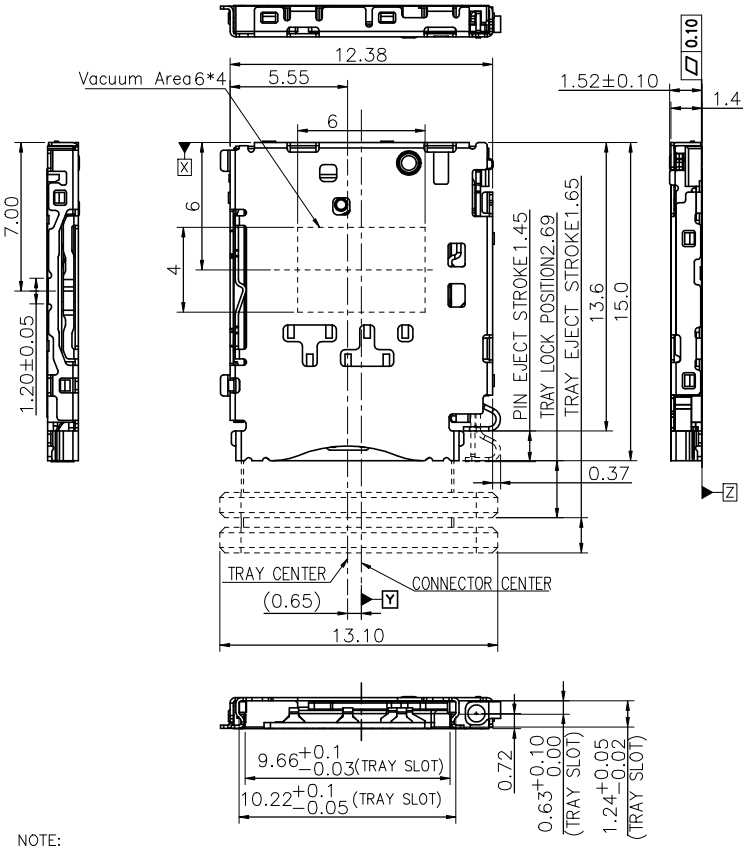
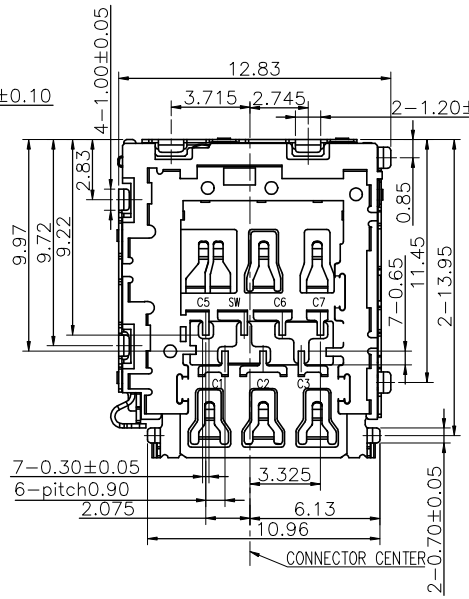
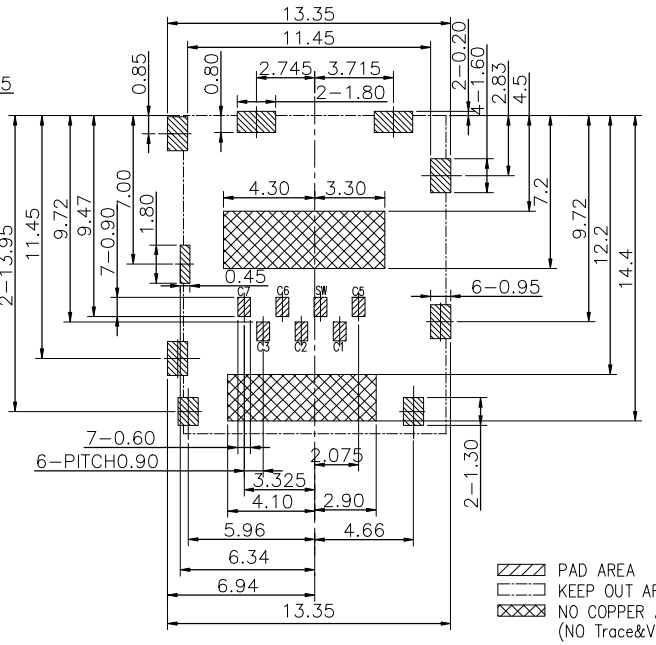
* 所有原料材质,生产制程,电镀必须符合HF要求







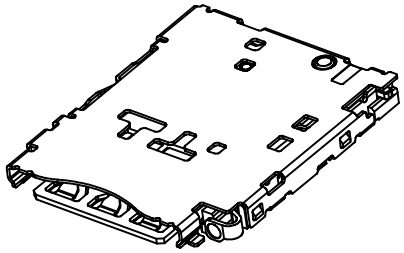
RECOMMEND P.C.B LAYOUT
(General tolerance ±0.05)

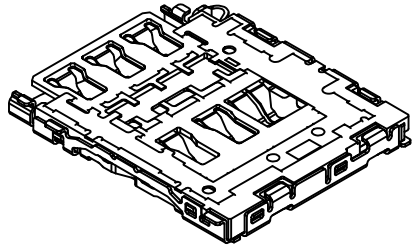
COMPOSITION OF DETECTION
CARD DETECT(SW)
C5 ○—○ SW
CARD DETECTION/SWITCH
CARD INSTALLATION:ON NON CARD:OFF

NOTE:
1. Material:
   1−1 Housing:High Temperature Thermoplastic,(LCP S475)Color Black UL 94V−0
   1−2 Contact: Phosphor Bronze(C5210R−H,T=0.08±0.01mm)
   B 1−3 Cover: SUS304−H T=0.15±0.03mm
2. Plating:
   2−1 Contact terminal:
   Contact area: Gold 1u" Min.
   Solder area: Gold 0.8u" Min .
   Underplating: Ni overall 50U" Min.
   2−2 Cover:
   Underplating: Ni overall 30U" Min.
   Solder area: Gold 0.8u" Min .
3. Specification:
   3−1.Current Rating :0.5A max.
   3−2.Contact Resistance: 50 mOhms max
   3−3.Insulation Resistance:1000 MOhms min./500VDC
   3−4.Dielectric Withstanding Voltage:500 V AC/1minute
   3−5.Operating Temperature:−40°C to+85°C
   3−6.Mating Cycles:5000 Insertions
4. Product Compliant to RoHs Directive 2002/95/EC and ELV 2000/53/EC
5. Part Must Comply Taisol HF WD−3−I−091 Specification.
6. Recommending A Metal More Than 0.15mm Thick.
   Please Confirm Solderadility, If Use A Metal Mask Less Than 0.15mm Thick.

SIM Card Pin Assignments

NANO SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
SW	CD/SW
C6	Vpp
C7	DATA





REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
B		修改图面Cover材质与实物相符 B	Aaron	2021.08.28
A	----	NEW RELEASE	PURE	2019.07.15

广东国连电子有限公司
GUANGDONG GUOLIAN ELECTRONICS CO.,LTD

DIMENSIONS INIT: mm
UNLESS OTHERWISE SPECIFIABLE

DIMENSION	TOLERANCE
X.X: ±	0.35
X.XX: ±	0.20
X.XXX: ±	0.10
ANGULAR: ±	2°

PRODUCT NAME : NANO SIM H1.5 CARD (无喷码)	DRAWING: Aaron	DATE: 2021.08.28	
PRODUCT NO. : NNB5FW1072E4	CHECK:	DATE:	
DRAWING NO. :	APPROVED:	DATE:	
	SCALE: 1:1	DWG ID: C D	REV.: B
			PAGE: 1 OF 1